

SMPS Columbus Scholarship

2026 Higher Education Student Application

THE SMPS COLUMBUS SCHOLARSHIP FUND

The Society for Marketing Professional Services® (SMPS) is a diverse community of marketing and business development professionals working together to move the Architecture, Engineering, and Construction (A/E/C) industry forward. SMPS members include **graphic designers, brand managers, marketers, business developers, social media managers, writers, public relations professionals, and more!**

Founded in 1981, SMPS Columbus is one of 58 Chapters committed to being the premier resource for those working in the built environment. With an average local membership of 130, SMPS Columbus' membership is largely comprised of individuals focused on marketing, graphic design, communications, and business development for professional services (engineering, architecture, landscape architecture, planning, and more) and construction companies.

The SMPS Columbus Scholarship Fund was established in 2017 to provide support to high school seniors, higher education students, and SMPS Columbus members who are pursuing and/or advancing their careers in the A/E/C industry.

SCHOLARSHIP BENEFITS

SMPS Columbus is committed to providing up to two (2) \$1,000 scholarships to two (2) current higher education students, selected by a Scholarship Selection Committee.

In addition to the monetary award, scholarship recipients are eligible to be paired with an SMPS Columbus member(s) to discuss their career path, networking, resume preparation, and related matters within the A/E/C industry.

SCHOLARSHIP CRITERIA

Applicants pursuing this scholarship must meet the following criteria:

- Applicants are only eligible to win this scholarship once.
- Applicant is currently enrolled in a two- or four-year public or private college, university, or trade school located within Ohio.
- Student is full-time (12 or more hours)
- Student has declared a major of Marketing, Business, Public Relations, Communications, Graphic Design, or a related degree.
- Holds a current GPA of 3.0 or higher

SUBMISSION INFORMATION

1. Complete applications must be received by 11:59 pm on Friday, March 20th. Incomplete and/or late applications will not be considered. Required materials:
 - Application (signed)
 - Narrative
 - Official Transcript
2. Email your submission to Meghan Allsop, SMPS Past President - meghan.allsop@ohm-advisors.com with the subject line: **SMPS Columbus 2026 Scholarship Application - Higher Ed**
3. Scholarship recipients will be notified of award by Wednesday, April 15th.
4. Scholarship funds shall be used for tuition and/or textbooks and supplies.
5. Questions? Contact Meghan Allsop, SMPS Past President at meghan.allsop@ohm-advisors.com.

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First Name _____ Middle Initial _____ Last Name _____

Street Address _____

City _____ State _____ Zip _____

Telephone # _____ Email Address _____

Currently Enrolled Higher Education Institution _____

Major Field of Study _____ Current GPA _____ Anticipated Graduation Date _____

List Your Awards / Honors / Personal Achievements

List Your Extracurricular Activities / Community Involvement

Attach a clear and concise narrative specifically addressing the following topics in the order listed. Narrative should be typewritten and no more than one page.

1. Why did you choose your major?
2. What are your career goals and how might they intersect with the architecture, engineering, or construction industry?
3. What impact would this scholarship have on you and your education?

Applicant Acknowledgment & Signature: I certify the information contained in this application and narrative is true. If awarded this scholarship, I certify the funds will be used for my tuition and/or textbooks and class supplies.

Applicant Signature _____ Date _____

Academic Advisor Acknowledgment & Signature: I have reviewed this application and the attached narrative. I certify the applicant is a current higher education student in good academic standing, and the information contained is true to the best of my knowledge.

Academic Advisor Signature _____ Date _____

Academic Advisor Name & Title (printed) _____

Email Address _____ Telephone # _____